

Ultra Low Capacitance ESD Protection Diode Array

APPLICATIONS

- ◆ Cellular Handsets & Accessories
- ◆ Cordless Phones
- ◆ Personal Digital Assistants (PDA's)
- ◆ Portable Instrumentation
- ◆ Notebooks & Handhelds
- ◆ Digital Cameras
- ◆ MP3 Players

IEC COMPATIBILITY

- ◆ IEC61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)

FEATURES

- ◆ 100 Watts Peak Pulse Power per Line ($t_p=8/20\mu\text{s}$)
- ◆ Protects up to four High-Speed I/O lines
- ◆ Ultra-small SC-89 package (1.6 x 1.6 x 0.55mm)
requires less than 2.9mm² of PCB area
- ◆ Working voltages : 5V
- ◆ Low leakage current

MECHANICAL CHARACTERISTICS

- ◆ SOT-563 Package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 3 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free

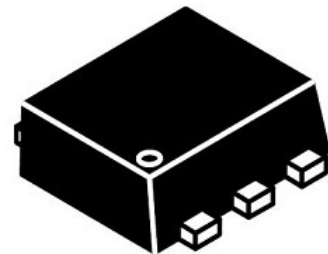
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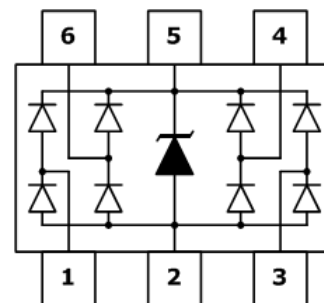
Email:sale1@leiditech.com

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SOT-563



PIN CONFIGURATION



DEVICE CHARACTERISTICS

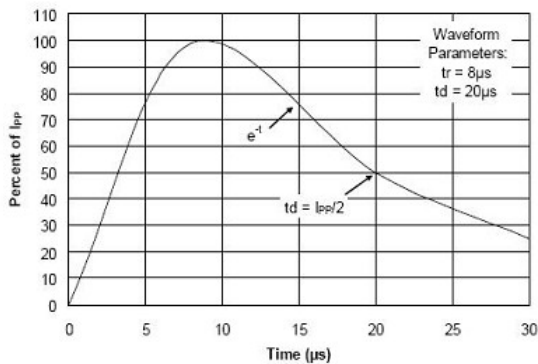
MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	100	Watts
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

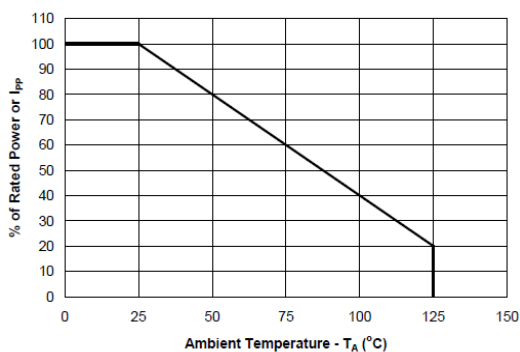
ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)

PART NUMBER	DEVICE MARKING	V _{RWM}	V _B	I _T	V _C	V _C		I _R	C _T
		(V) (max.)	(V) (min.)	(mA)	@1A (max.)	(max.)	(@A)	(µA) (max.)	(pF) (typ.)
ULC0504T6	4T	5	6	1	9.8	15	2	1	0.7

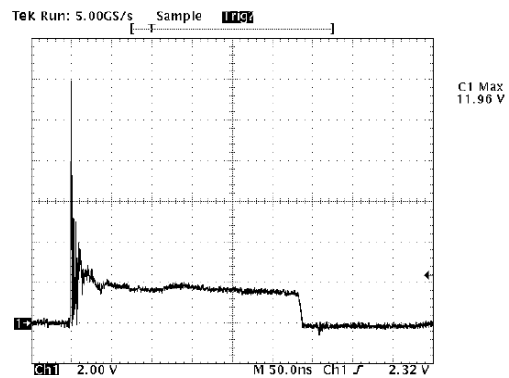
Pulse Waveform



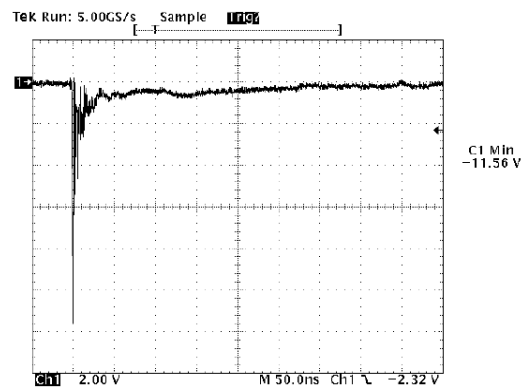
Power Derating Curve



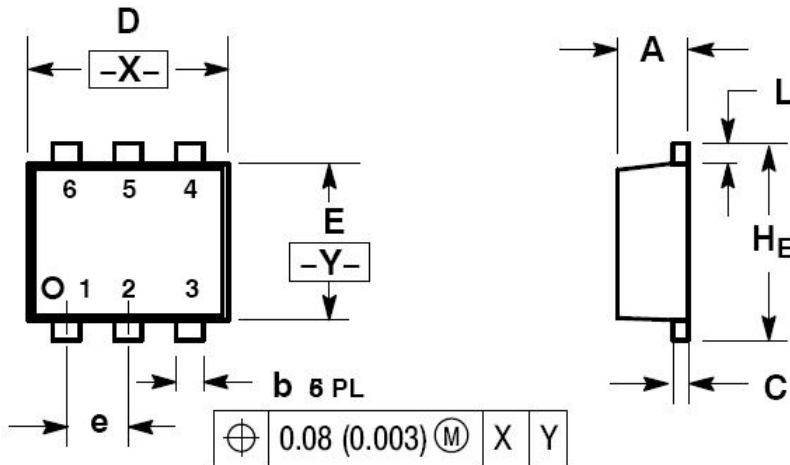
ESD Clamping
(8kV Contact per IEC 61000-4-2)



ESD Clamping
(-8kV Contact per IEC 61000-4-2)

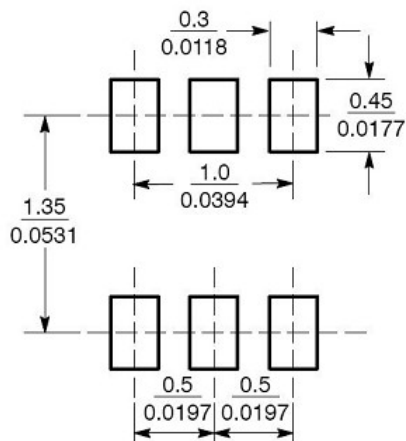


SOT-563 PACKAGE OUTLINE & DIMENSIONS



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.5 BSC			0.02 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H _E	1.50	1.60	1.70	0.059	0.062	0.066

* SOLDERING FOOTPRINT



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